



Conference Agenda - Wednesday September 18, 2019

Welcome Coffee and Registration - Networking and Designer Expo

Keynotes

Anirudh Devgan: President, Cadence
 Shlomit Weiss, Senior Vice President Silicon Engineering, Mellanox
 Anat Shaked, Co-Founder and CEO, Nexite
 Dov Moran, Managing Partner, Grove Ventures

Networking and Designer Expo

	Custom IC and Analog Grand Ballroom C	Full-Flow Digital Design and Signoff Royal Ballroom H	SoC and System Verification Grand Ballroom B	IP and Block Verification Grand Ballroom A	PCB Design and System Analysis Royal Ballroom I	Cloud-Based Design Royal Ballroom J	IP Solutions Meeting Room 4	Education Services Meeting Room 5
8:45-09:45	Welcome Coffee and Registration - Networking and Designer Expo							
09:45-11:00	Keynotes Anirudh Devgan: President, Cadence Shlomit Weiss, Senior Vice President Silicon Engineering, Mellanox Anat Shaked, Co-Founder and CEO, Nexite Dov Moran, Managing Partner, Grove Ventures							
11:00-11:45	Networking and Designer Expo							
11:45-12:15	CUS01 Technology Overview <i>Cadence</i>	DSG01 Technology Overview (FED) <i>Cadence</i>	SVG01/02 + IBV01/02 Technology Overview <i>Cadence</i>		PCB01 A Platform for System Design and Analysis for 5G and Radar Applications <i>Cadence</i>	Cloud01 + Cloud02 Rapid Innovation Using Cloud for Design and Verification <i>Amazon Web Services with Annapurna</i>	IP01 Choosing a DSP for Hearables <i>Cadence</i>	ES01 + ES02 The New Design Approach: High-Level Synthesis Introduction for RTL Designers <i>Cadence</i>
12:15-12:45	CUS02 Technology Overview <i>Cadence</i>	DSG02 Technology Overview (ICD) <i>Cadence</i>			PCB02 + PCB03 Introducing New OrCAD 17.4 Release <i>EDAIS</i>		IP02 Highly Efficient, Scalable Vision and AI Processors IP for the Edge <i>Cadence</i>	
12:45-13:15	CUS03 Automated RF and Analog Design <i>Intel</i>	DSG03 Innovus Mixed Macro Placer <i>Mellanox</i>	SVG03 Enabling Early FW Development and Debug Using Emulation Platform <i>Intel</i>	IBV03 Hybrid Verification Approach of Embedded Processor <i>Intel</i>	IP03 Fusion F1 DSP, Ideal DSP for NB-IoT Modems <i>Cadence</i>			
13:15-14:00	Lunch / Designer Expo / Networking							
14:00-14:30	CUS04 How We Convert Tool Transition to Success Story! <i>Intel</i>	DSG04 High-Level Synthesis Will Supercharge Your IP Development <i>Intel</i>	SVG04 Hybrid Virtual + Emulation SoC Platform for SW-Drivers Validation <i>Intel-Mobileye</i>	IBV04 Formal Verification of a Custom uController – A Case Study <i>Vierst</i>	PCB04 Addressing the Challenges of Electrical/Thermal Co-Simulation <i>Cadence</i>	Cloud03 Lessons Learned from Assisting the Early Adopters of Cloud-Based IC Design <i>Cadence</i>	IP04 Spring Hill – Intel’s Data Center Inference Chip <i>Intel</i>	
14:30-15:00	CUS05 Mixed Signal Simulation of a 12 bit 50 MS/s Dual Channel Time Domain Two Step ADC <i>Analog Value</i>	DSG05 BIU Experience: Pegasus and Common UI <i>Bar-Ilan University</i>	SVG05 Pre-Silicon Verification of an Ethernet Packet Processor with Industrial Strength Traffic Generation <i>Marvell</i>	IBV05 Enhanced Test Composition and Generation by Integration <i>Texas Instruments</i>	PCB05 What’s New in Electrical Extraction and Analysis <i>Cadence</i>	Cloud04 + Cloud05 Azure Deployment for Silicon Design <i>Microsoft with TSMC</i>	IP05 Hearing Sense in Smart Devices <i>Alango Technologies</i>	ES03 Writing Good SKILL Code <i>Cadence</i>
15:00-15:30	CUS06 PVS Voltage Aware DRC Using PVL Td DFM Property Advance Commands <i>TowerJazz</i>	DSG06 Equivalence Check with Low Power <i>Intel</i>	SVG06 Protium Platform Usage in Early SW Bring-Up of SoC <i>Altair</i>	IBV06 Automotive V Model Verification Flow <i>Autotalks</i>	PCB06 Multitasking PCB Layout with Several Designers to Reduce Project Time <i>Nistec</i>	IP06 The Power of Data-Over-Sound <i>Sonarax</i>		
15:30-16:00	CUS07 Managing Design Traceability for AMS Tapeouts <i>ClioSoft</i>	DSG07 Implementation of Large Scale Design Changes with Conformal ECO <i>Magicleap</i>	SVG07 Using PSS to Accelerate Validation Stimuli Development and Execution Efficiency <i>Intel</i>	IBV07 Modeling DMA in Fake Processors Simulations Using DPI-C <i>Satisfy</i>	PCB07 Capture Constraint Manager – Front to Back Constraints <i>EDAIS</i>	IP07 Addressing the State of Safety and Security in Today’s Vehicles <i>Green Hills Software</i>		
16:00-16:30	Happy Hour in Designer Expo							
16:30-17:30	Best Presentation Awards and Entertainment							